

DS3680 QUAD TELEPHONE RELAY DRIVER

SLRS014C – MARCH 1986 – REVISED SEPTEMBER 1995

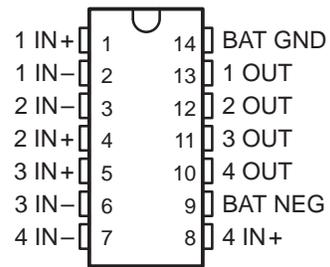
- Designed for –52-V Battery Operation
- 50-mA Output Current Capability
- Input Compatible With TTL and CMOS
- High Common-Mode Input Voltage Range
- Very Low Input Current
- Fail-Safe Disconnect Feature
- Built-in Output Clamp Diode
- Direct Replacement for National DS3680 and Fairchild μ A3680

description

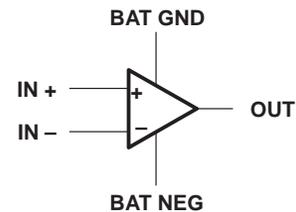
The DS3680 telephone relay driver is a monolithic integrated circuit designed to interface –48-V relay systems to TTL or other systems in telephone applications. It is capable of sourcing up to 50 mA from standard –52-V battery power. To reduce the effects of noise and IR drop between logic ground and battery ground, these drivers are designed to operate with a common-mode input range of ± 20 V referenced to battery ground. The common-mode input voltages for the four drivers can be different, so a wide range of input elements can be accommodated. The high-impedance inputs are compatible with positive TTL and CMOS levels or negative logic levels. A clamp network is included in the driver outputs to limit high-voltage transients generated by the relay coil during switching. The complementary inputs ensure that the driver output is off as a fail-safe condition when either output is open.

The DS3680 is characterized for operation from 0°C to 70°C.

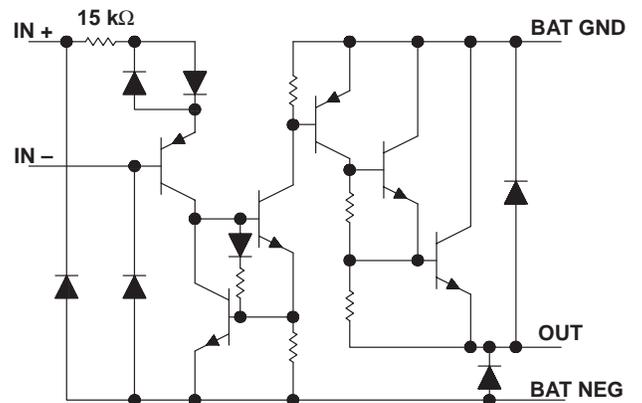
D OR N PACKAGE
(TOP VIEW)



symbol (each driver)



schematic diagram (each driver)



All resistor values shown are nominal.

switching characteristics $V_{BAT-} = -52\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{on}	Turn-on time	$V_{ID} = 3\text{-V pulse}$, $R_L = 1\text{ k}\Omega$, $L = 1\text{ H}$, See Figure 2		1	10	μs
t_{off}	Turn-off time			1	10	μs

PARAMETER MEASUREMENT INFORMATION

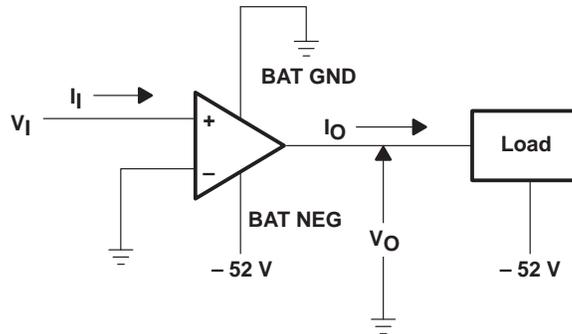


Figure 1. Generalized Test Circuit, Each Driver

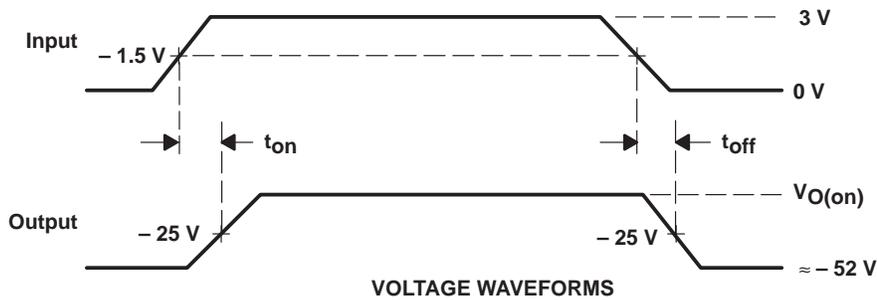
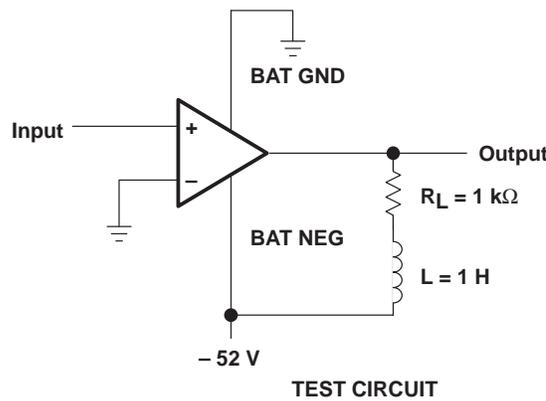


Figure 2. Test Circuit and Voltage Waveforms, Each Driver

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APPLICATION INFORMATION

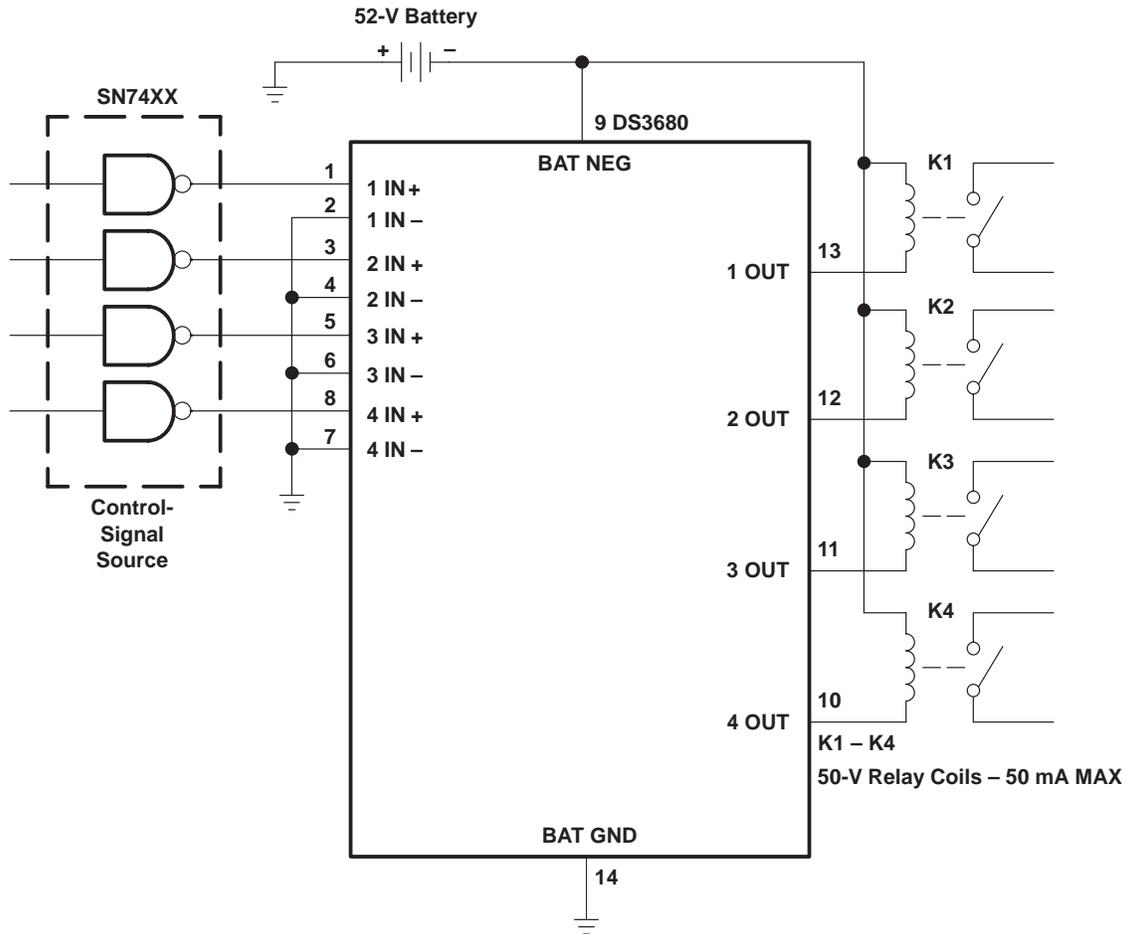


Figure 3. Relay Driver

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DS3680D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS3680	Samples
DS3680DE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS3680	Samples
DS3680N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	DS3680N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

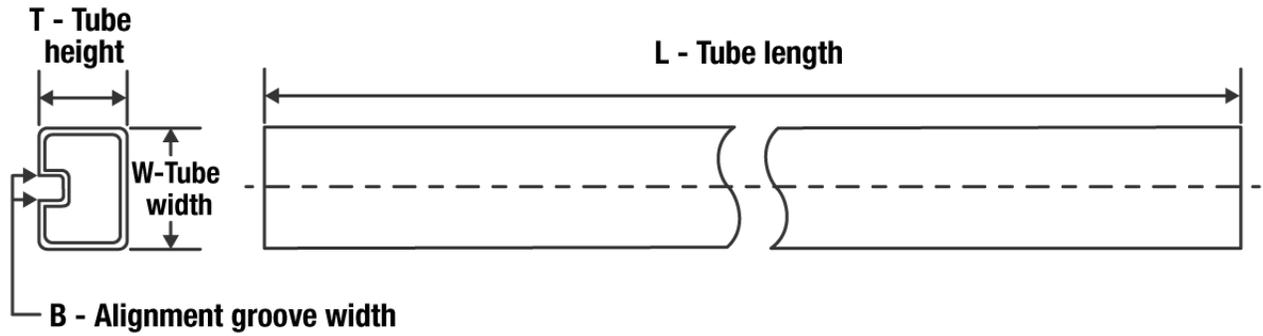
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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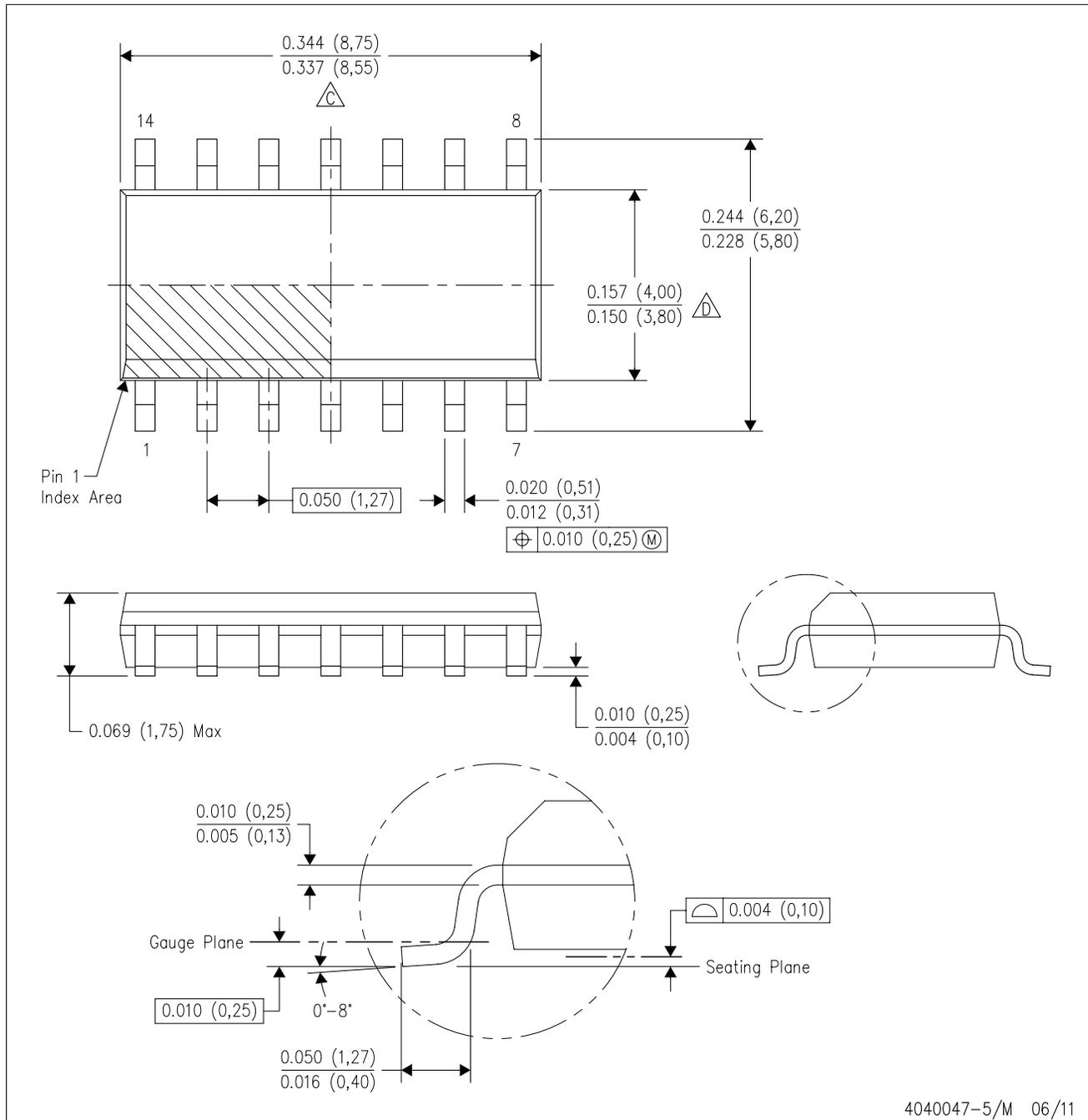
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS3680D	D	SOIC	14	50	506.6	8	3940	4.32
DS3680DE4	D	SOIC	14	50	506.6	8	3940	4.32
DS3680N	N	PDIP	14	25	506	13.97	11230	4.32

D (R-PDSO-G14)

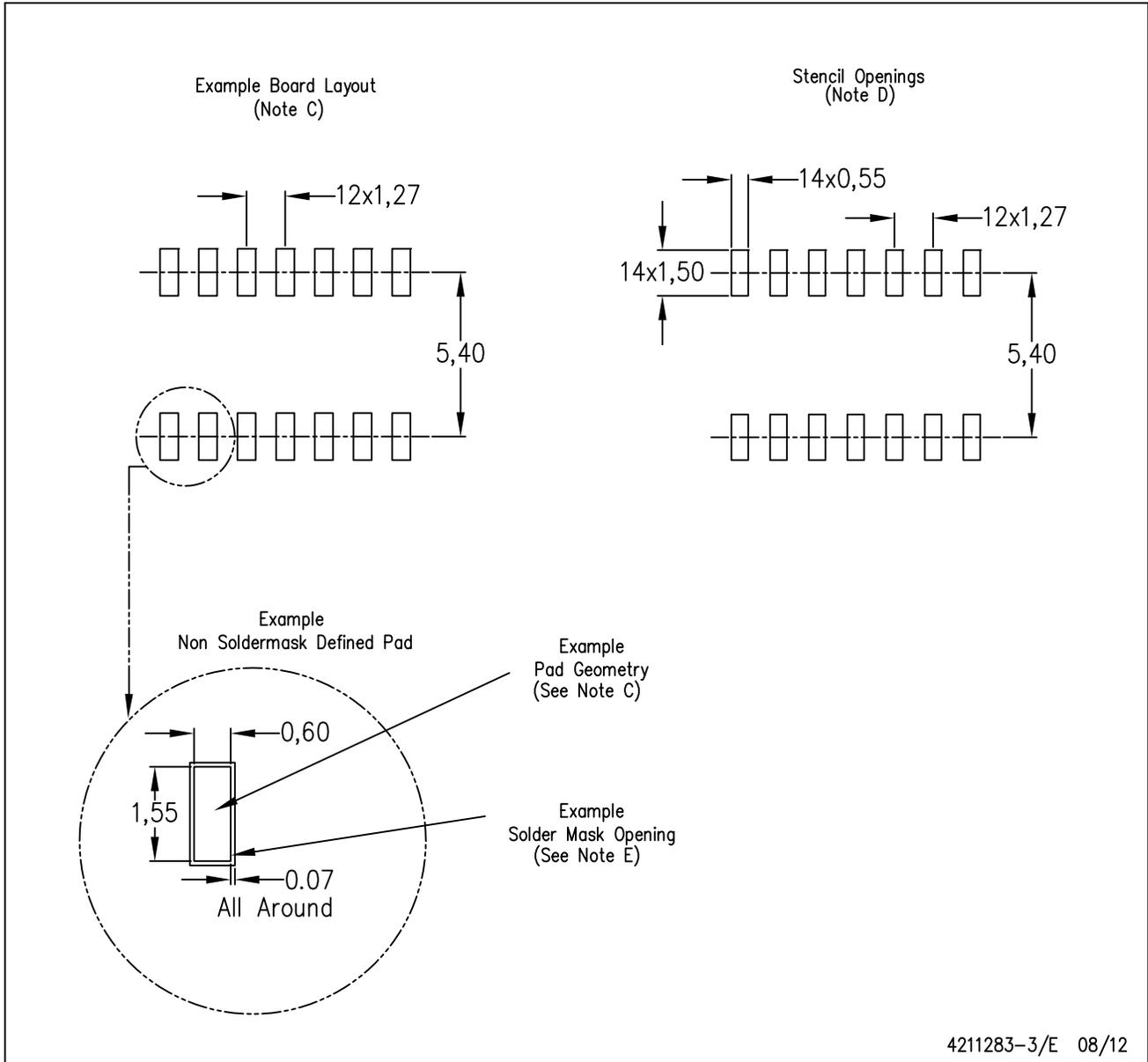
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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